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PATENT  
Attorney Docket No. 00-103

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Margaret S. Fyfield

Serial No. 09/731,596

Filed: December 6, 2000

For: Probing Fixture and Method  
of Semiconductor Wafer



Group Art Unit:

Examiner:

**CERTIFICATE OF MAILING BY FIRST CLASS MAIL**

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

The undersigned hereby certifies that the attached Information Disclosure Statement; Form PTO-1449; Certificate of Mailing by First Class Mail; and Return Card, relating to the above application, were deposited as "First Class Mail," with the United States Postal Service, addressed to The Commissioner of Patents and Trademarks, Washington, D.C. 20231, on this 6th day of March, 2001.

03/06/01  
Date

Nathaniel Porter  
Mailer

3/6/01  
Date

John R. Ley  
Registration No. 27,453  
ATTORNEY FOR APPLICANT

JOHN R. LEY, LLC  
5299 DTC Boulevard, Suite 610  
Greenwood Village, Colorado 80111-3327  
Telephone: (303) 740-9000  
Facsimile: (303) 740-9042

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**INFORMATION DISCLOSURE STATEMENT**

Honorable Commissioner of  
Patents and Trademarks  
Washington, D.C. 20231

Sir:

The Examiner may wish to consider the following references during the examination  
of the above-identified application:

Other Documents

Gary Shade and Kendall Scott Wills, *Photoemission Microscopy*, 1997 ASM  
International, pp. 181-182.

B. Bossmann, P. Baur Schmidt, K. Hussey, and E. Black, *Failure Analysis  
Techniques with the Confocal Laser Scanning Microscope*, ISTFA '92: The 18<sup>th</sup>  
International Symposium for Testing & Failure Analysis, October 1992, pp. 351-361

Nevil M. Wu, Kevin Weaver, James H. Lin, *Failure Analysis from Back Side of Die*,  
ISTFA '96: 22<sup>nd</sup> International Symposium for Testing and Failure Analysis,  
November 1996, 7 pages

TW. Joseph, A.L. Berry, B. Bossman, *Infrared Laser Microscopy of Structures on Heavily Doped Silicon*, ISTFA '92: The 18<sup>th</sup> International Symposium for Testing & Failure Analysis, October 1992, pp. 1-7

D.L. Barton, P. Tangyungyong, J.M. Soden, A.Y. Liang, F.J. Low, A.N. Zaplatin, K. Shivanandan, and G. Donohoe, *Infrared Light Emission from Semiconductor Devices*, Proceedings of the 22<sup>nd</sup> International Symposium for Testing and Failure Analysis, November 1996, pp. 9-17

Chun-Cheng Tsao, Steven, Kasapi, and Kurt Hurley, *Backside waveform probing of CMOS devices using infrared laser at wavelength of 1064 nm*, 6 pages

C. Chiang, N. Khurana, D.T. Hurley, and K. Teasdale, *Backside Emission Microscopy for Integrated Circuits on Heavily Doped Substrate*, Proceedings from the 24<sup>th</sup> International Symposium for Testing and Failure Analysis, November 1998, pp. 447-453

Kendall Scott Wills, Terril Lewis, Greg Billus, Hai Hoang, *Optical Beam Induced Current Applications for Failure Analysis of VLSI Devices*, 1997 ASM International, pp. 21-26

Yeoh Eng Hong and Martin Tay Tiong We, *The application of novel Failure Analysis Techniques for Advanced Multi-Layered CMOS devices*, 6 pages

T. Koyama, Y. Mashiko, M. Sekine, H. Koyama and K. Horie, *New non-bias optical beam induced current (NB-OBIC) techniques for evaluation of A1 interconnects*, 1995 IEEE, pp. 228-233

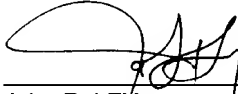
Said F. Al-sarawi, *Tape-Automated Bonding*, Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, pp. 1-2

Said F. Al-sarawi, *Solder Bump Bonding*, Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, 1 page

Attached is a completed Form PTO-1449 for the Examiner's convenience in citing these references. Copies of the above identified references are also enclosed.

Signed at Greenwood Village, Colorado this 6<sup>th</sup> day of March, 2001.

Respectfully submitted,

A handwritten signature in black ink, appearing to be 'John R. Ley', is written over a horizontal line.

John R. LEY  
Registration No. 27,453  
ATTORNEYS FOR APPLICANT

JOHN R. LEY, LLC  
5299 DTC Boulevard, Suite 610  
Greenwood Village, Colorado 80111-3327  
Telephone: (303) 740-9000  
Facsimile: (303) 740-9042

FORM PTO-1449 (Rev. 2-82)	U.S. DEPART. OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 00-103	SERIAL NO. 09/731,596
		APPLICANT Margaret S. Fyfield	
		FILING DATE December 6, 2000	GROUP

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

(Use several sheets if necessary)

## U.S. PATENT DOCUMENTS

EXAM. INIT.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPRO- PRIATE

## FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRAN- SLATION	
					YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	Gary Shade and Kendall Scott Wills, <i>Photoemission Microscopy</i> , 1997 ASM International, pp. 181-182.
	B. Bossmann, P. Baur Schmidt, K. Hussey, and E. Black, <i>Failure Analysis Techniques with the Confocal Laser Scanning Microscope</i> , ISTFA '92: The 18 <sup>th</sup> International Symposium for Testing & Failure Analysis, October 1992, pp. 351-361
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	T. Koyama, Y. Mashiko, M. Sekine, H. Koyama and K. Horie, <i>New non-bias optical beam induced current (NB-OBIC) techniques for evaluation of A1 interconnects</i> , 1995 IEEE, pp. 228-233
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	Said F. Al-sarawi, <i>Solder Bump Bonding</i> , Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, 1 page

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.